

Special Issue Film Materials and Devices

Call for Papers

Historically, thin films have been used for more than a half century in making electronic devices, optical coatings, instrument hard coatings, and decorative parts. The thin film is a traditional well-established material technology. However, thin film technology is still being developed on a daily basis since it is a key in the twenty-first century development of new materials such as nanometer materials and/or a man-made superlattices. The goal of this special issue is to provide a platform for scientists and academicians all over the world to promote, share, and discuss various new issues and developments in the area of **film materials and devices**.

In this special issue, we invite front-line researchers and authors to submit original research and review articles that explore **film materials and devices**. In this special issue, potential topics include, but are not limited to:

- Ceramic thin films
- Electronic film materials
- Thin film technology and deposition processes
- Structural control of compound thin films
- Properties of thin SiO₂ Layers
- Semiconductor thin film material
- Nanometer thin film materials
- Dielectric film materials
- Thin film processes
- Deposition of compound thin films

Authors should read over the journal's <u>For Authors</u> carefully before submission. Prospective authors should submit an electronic copy of their complete manuscript through the journal's <u>Paper Submission System</u>.

Please kindly specify the "**Special Issue**" under your manuscript title. The research field "**Special Issue** –*Film Materials and Devices*" should be selected during your submission.

Special Issue timetable:

Submission Deadline	February 15th, 2025
Publication Date	April 2025

Guest Editor:

Dr. Yang Li, Northwest Institute for Non-ferrous Metal Research, China.



For further questions or inquiries Please contact Editorial Assistant at <u>msce@scirp.org</u>